



FOR IMMEDIATE RELEASE

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**Aehr Test Systems to Announce Third Quarter Fiscal 2017 Financial Results
on March 30, 2017**

Fremont, CA (March 21, 2017) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it will report financial results for its third quarter of fiscal 2017 ended February 28, 2017 on Thursday, March 30, 2017 following the close of the market. The Company will host a conference call and webcast at 5:00 p.m. Eastern time to discuss the results.

What: Aehr Test Systems third quarter fiscal 2017 financial results conference call

When: Thursday, March 30th at 5:00 p.m. Eastern Time (2:00 p.m. PT)

Dial in Number: To access the live call, dial **888-656-7430** (US and Canada) or **913-312-0423** (International) and give the participant passcode **4371442**.

Webcast: To access the live webcast, please visit the investor relations section at www.aehr.com.

Call Replay: A phone replay of the call will be available approximately two hours following the end of the call through 8:00 p.m. ET on Thursday, April 6, 2017. To access the replay dial-in information, please click [here](#).

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip and integrated optical devices. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit the Company's website at www.aehr.com.

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